



# Material Composition Declaration

## EPC2050

Company Name	Efficient Power Conversion (EPC)	Issue Date:	4/4/2022
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	4.8 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	4.4041	90.8128	94.3655	908128
	Silicon oxide	7631-86-9	0.0166	0.3428		3428
	Silicon nitride	12033-89-5	0.0116	0.2388		2388
	Gallium nitride	25617-97-4	0.0393	0.8095		8095
	Aluminum	7429-90-5	0.0355	0.7313		7313
	Aluminum nitride	24304-00-5	0.0149	0.3073		3073
	Titanium	7440-32-6	0.0004	0.0082		82
	Titanium nitride	25583-20-4	0.0017	0.0344		344
	Copper	7440-50-8	0.0006	0.0122		122
	Tungsten	7440-33-7	0.0035	0.0729		729
	Polyimide		0.0483	0.9952		9952
Under Bump Metal	Titanium	7440-32-6	0.0002	0.0035	0.0383	35
	Copper	7440-50-8	0.0017	0.0348		348
Solder Bump	Copper	7440-50-8	0.0169	0.3482	5.5962	3482
	Nickel	7440-02-0	0.0101	0.2077		2077
	Tin	7440-31-5	0.2400	4.9495		49495
	Silver	7440-22-4	0.0044	0.0907		907
Sum in total:			4.8497	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.